





Data Sheet Dexnyl[©] 330 PI-s-Powders Nat.

Product Description

Thermosetting Polyimide (PI-s), natural granule suitable for molding and compounding

Applications

- Can be used as a compounding material to produce parts and/or coatings with enhanced thermal properties
- To produce ultra-high temperature, self-lubricant and wear resistance semifinished and finished parts through compression molding or direct forming
- High strength and heat resistance gears, bearing, sealing elements, etc.
- To produce non-toxic fire retardant products

Properties	Units	Dexnyl [©] 330 PI-s
Density	g/cm ³	1.30
Glass Transistion Temperature≥	°C	330
Thermal Expansion Coefficient	10⁻⁵/°C	6.0
Tensile Strength ≥	MPa	40
Tensile Modulus	GPa	-
Elongation at Break≥	%	3.5
Flexural Modulus	GPa	2.70
Compressive Strength≥	MPa	150
Impact Strength≥	KJ/m ²	12.0
Friction Coefficient	-	0.25-0.30
Dielectric Coefficient	-	3.4
Dielectric Loss	-	2.1x10 ⁻⁴
Breakdown Potential≥	KV/mm	25
Volume Resistivity≥	Ω.m	1.0×10 ¹⁶
Shore D-Hardness≥	HD	85.0
Water absorption <	%	0.3

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For information about divergent properties do not hesitate to contact us. On request we advise you regarding the most appropriate component design and the definition of material specifications more suitable to your application data. Notwithstanding, the customer bears all the responsibility for the thorough examination of suitability, efficiency, efficacy and safety of the chosen products in pharmaceutical applications, medical devices or other end uses. Status: June 2019